Product End-of-Life Disassembly Instructions

Product Category: Monitors and Displays

Marketing Name / Model [List multiple models if applicable.]
HP EliteDisplay E221 21.5-inch LED Backlit Monitor

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	4
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		17
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		1
External electrical cables and cords		5
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0

Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 Screw driver of "+" type	
Description #2 Hexagonal nut screw driver for DVI and D-SUB connector	
Description #3	
Description #4	
Description #5	

3.0 Product Disassembly Process
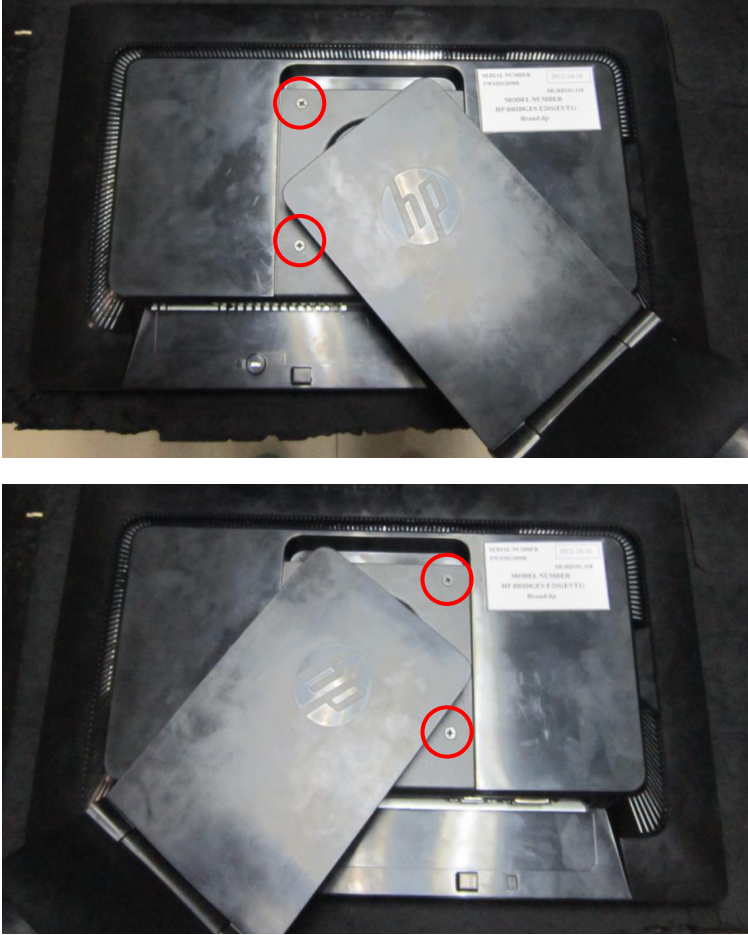
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:
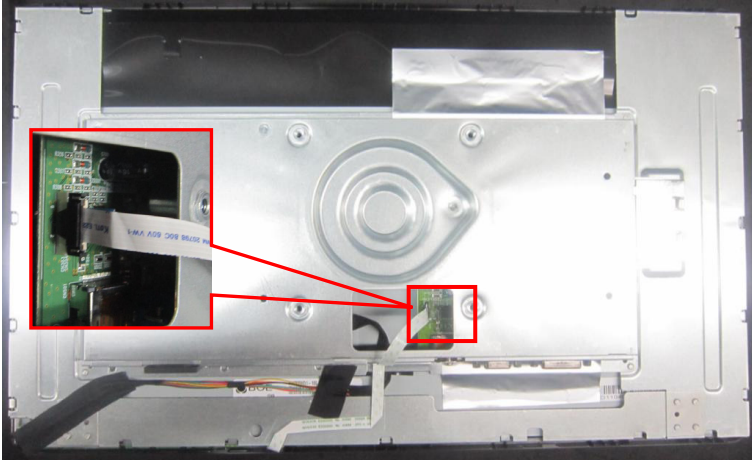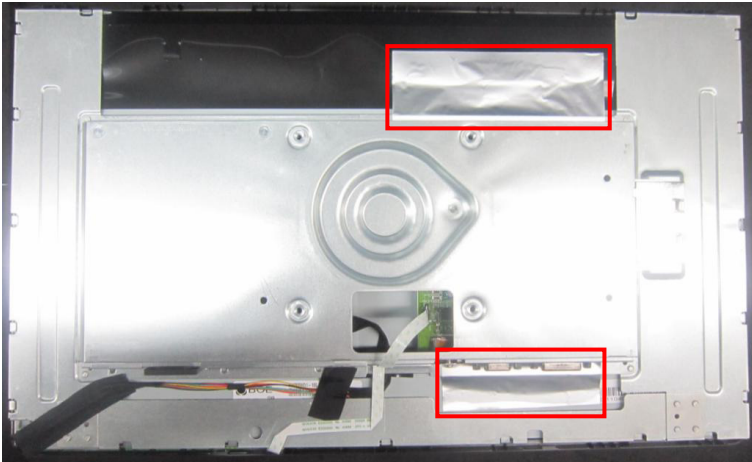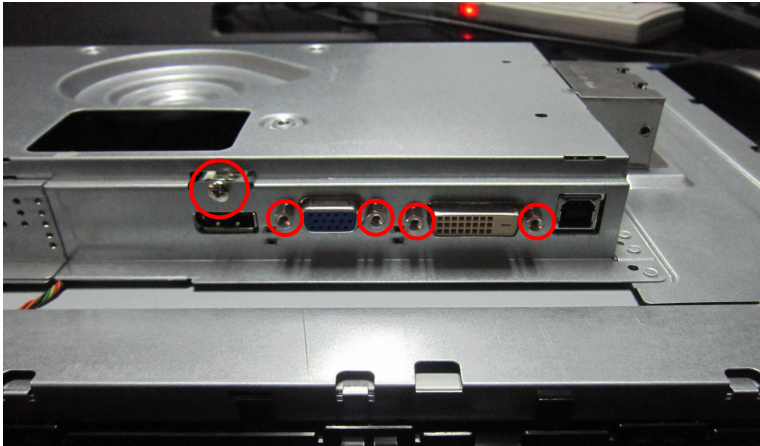
1. Lay the monitor on a flat, soft and clean surface.
2. Remove the screws in red to remove the stand.
3. Remove the key pin.
4. Remove the aluminum foil.
5. Remove the screws in the red.
6. Remove the BKT and bezel.
7. Remove the screws in red to remove the key board.
8. Remove the screws.
9. Remove the tape and the lamp pin
10. Remove the anti-static rubber and the FFC pin.
11. Remove the mainframe and panel
12. Remove the MYLAR and the the tape
13. Remove the screws in red to remove the main board and power board
14. Remove the Power board connect pin and the USB board connect pin
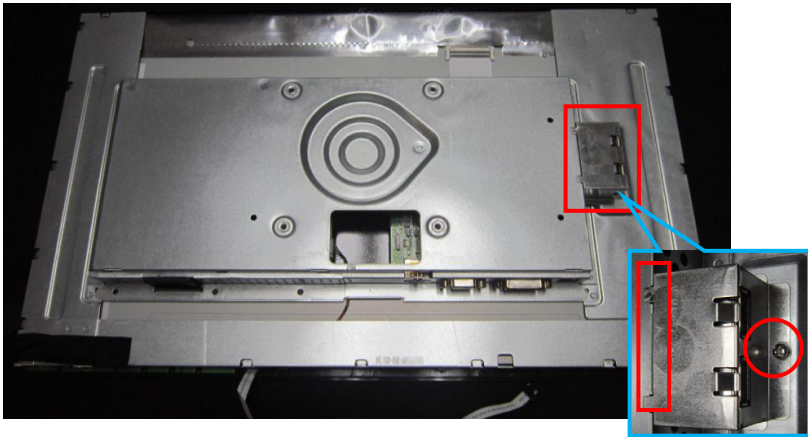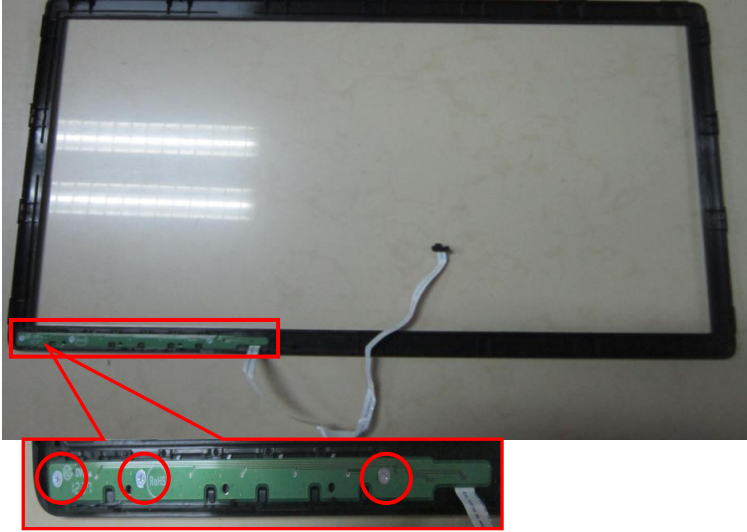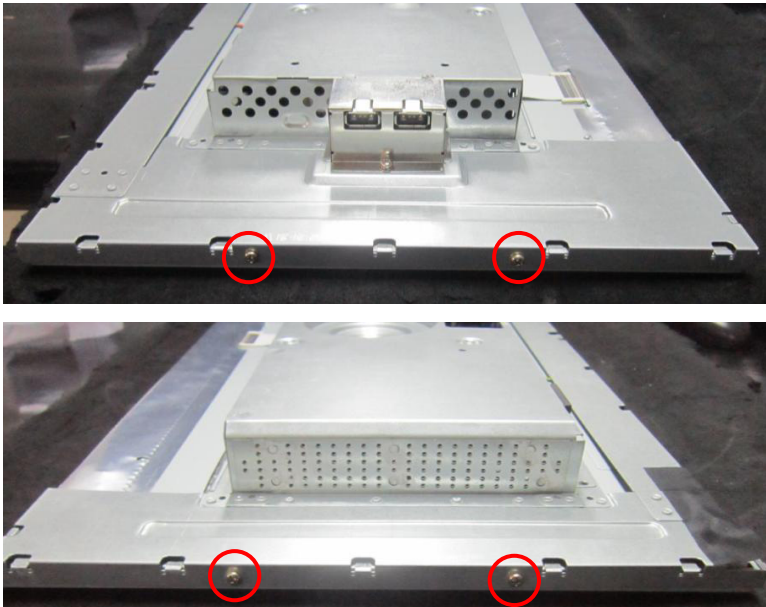15. Remove the USB board
16.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
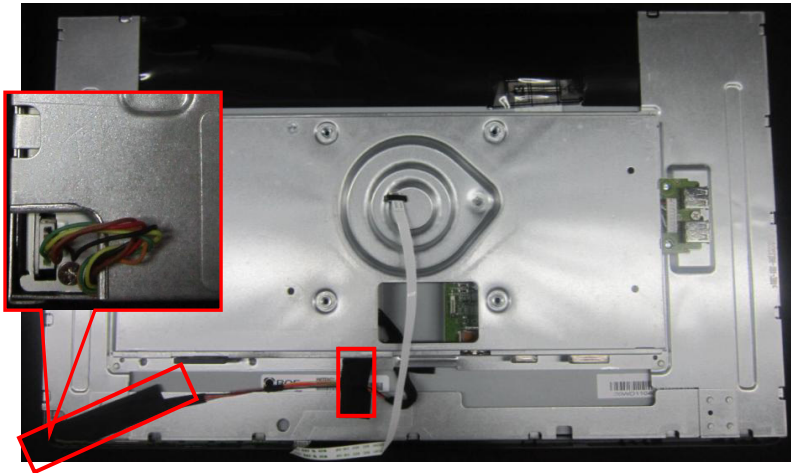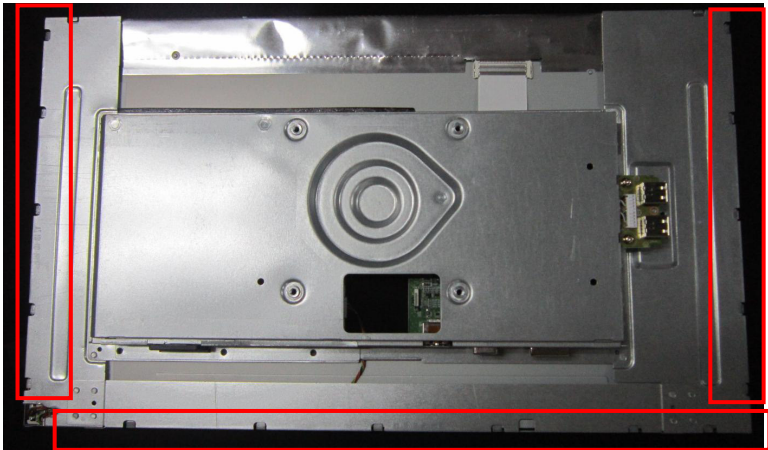
Pls. refer the attached:
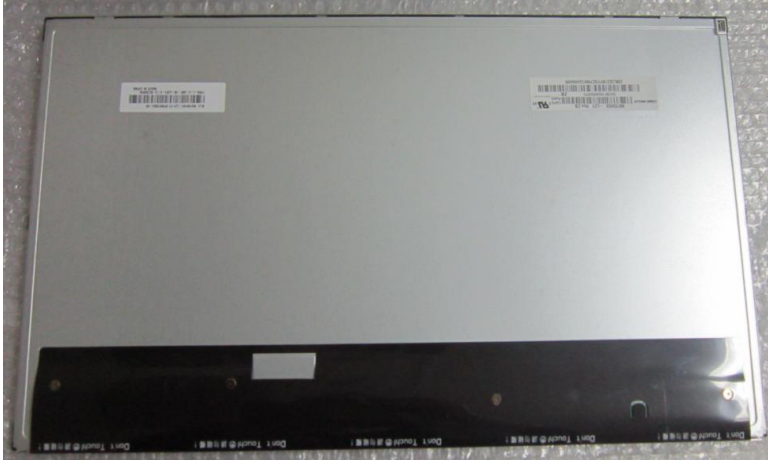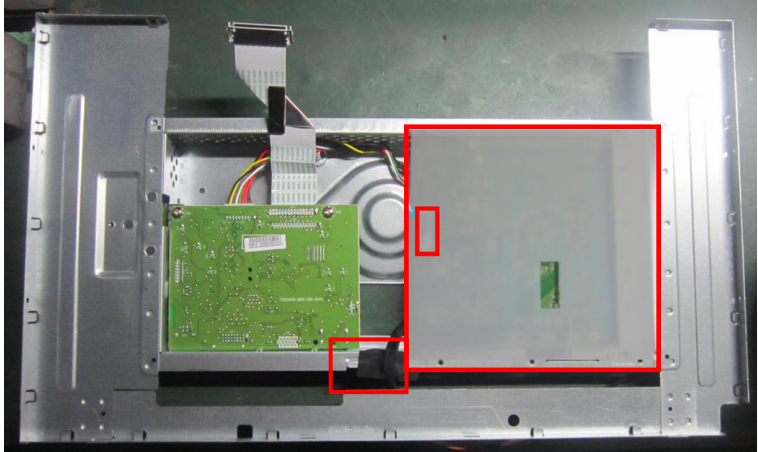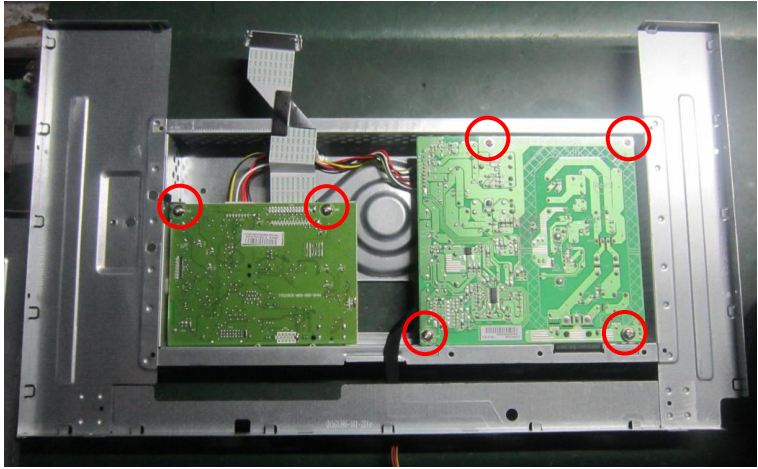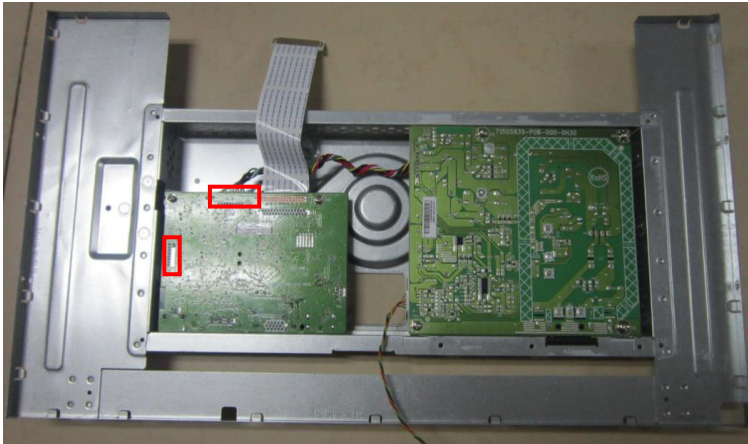
11. Mechanical Instructions

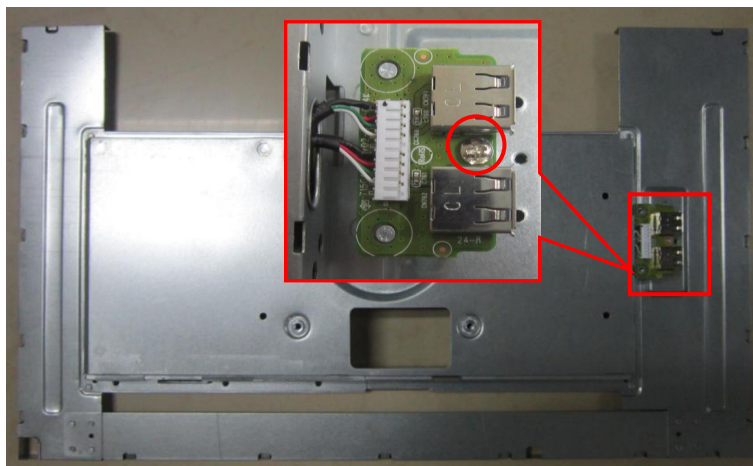| Step	Figure	Description
Preparation		Lay the monitor on a flat, soft and clean surface.
Remove the stand		Remove the screws in red to remove the stand.

Remove the key pin		Remove the key pin.
Remove the aluminum foil		Remove the aluminum foil.
Remove the screws		Remove the screws in the red.

Remove the BKT and bezel		Remove the BKT and bezel.
Remove the key board		Remove the screws in red to remove the key board.
Remove the screws		Remove the screws.

Remove the tape and the lamp pin		Remove the tape and the lamp pin
Remove the anti-static tape and the FFC pin		Remove the anti-static rubber and the FFC pin.
Remove the mainframe		Remove the mainframe

Panel		panel
Remove the MYLAR and the tape		Remove the MYLAR and the tape
Remove the main board and power board		Remove the screws in red to remove the main board and power board
Remove the connector		Remove the Power board connect pin and the USB board connect pin

Remove the USB board		Remove the USB board